

IN THE CLAIMS:

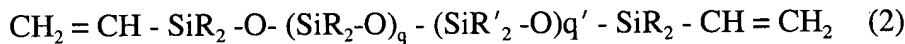
Claims 1-5. (Cancelled)

6. (Amended) A method of preparing a molding, comprising the steps of:

(a) providing a hydrosilylated polymer obtained by reacting at least one hydridosilsesquioxane compound of the following formula (1):



wherein n is an integer of 4-1000, with at least one divinylsiloxane compound of the following formula (2):



wherein R and R' are independently selected from alkyl groups, substituted alkyl groups, aryl groups and substituted aryl groups, and q and q' are each an integer of 0 or more, and

(b) heating the hydrosilylated polymer in an atmosphere of an inert gas and at a temperature higher than the softening point or melting point thereof in a mold cavity to cure the polymer.

7. (Originally presented) A method as claimed in claim 6, wherein step (b) is performed under a reduced pressure.

8. (Cancelled).

9. (Originally presented) A method as claimed in claim 6, wherein n in the formula (1) of said hydridosilsesquioxane is 8.

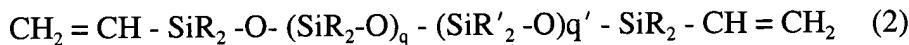
10. (Originally presented) A method as claimed in claim 6, wherein said heating is at 50-250°C.

11. (Newly Added) A method of preparing a molding, comprising the steps of:

(a) providing a hydrosilylated polymer obtained by reacting at least one hydridosilsesquioxane compound of the following formula (1):



wherein n is an integer of 4-1000, with at least one divinylsiloxane compound of the following formula (2):



wherein R and R' are independently selected from alkyl groups, substituted alkyl groups, aryl groups and substituted aryl groups, and q and q' are each an integer of 0 or more, and

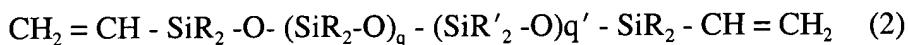
(b) heating the hydrosilylated polymer under a reduced pressure and at a temperature higher than the softening point or melting point thereof in a mold cavity to cure the polymer.

12. (Newly added) A method of preparing a molding, comprising the steps of:

(a) providing a hydrosilylated polymer obtained by reacting at least one hydridosilsesquioxane compound of the following formula (1):



wherein n is an integer of 4-1000, with at least one divinylsiloxane compound of the following formula (2):



wherein R and R' are independently selected from alkyl groups, substituted alkyl groups, aryl groups and substituted aryl groups, and q and q' are each an integer of 0 or more; and

(b) heating the hydrosilylated polymer at a temperature higher than the softening point or melting point thereof under a reduced pressure;

(c) then heating the hydrosilylated polymer at ambient pressure; and

(d) heating the product obtained in step (c) in a mold cavity to complete the curing of the

hydrosilylated polymer, steps (b) and (c) being successively repeated at least twice before step (d).

13. (Newly added) A method as claimed in claim 12, wherein n in the formula (1) of said hydridosilsesquioxane is 8.

14. (Newly added) A method as claimed in claim 12, wherein said heating is at 50-250°C.

15. (Newly added) A method as claimed in claim 12 wherein said step (c) is performed in an inert gas atmosphere.

16. (Newly added) A method as claimed in claim 15 wherein said step (d) is performed in an inert atmosphere.

17. (Newly added) A method as claimed in claim 12 wherein said step (d) is performed in an inert gas atmosphere.

18. (Newly added) A method as claimed in claim 17 wherein said step (b) is repeated at

successively higher temperatures.

19. (Newly added) A method as claimed in claim 16 wherein said step (b) is repeated at successively higher temperatures.

20. (Newly added) A method as claimed in claim 15 wherein said step (b) is repeated at successively higher temperatures.

21. (Newly added) A method as claimed in claim 12 wherein said step (b) is repeated at successively higher temperatures.